

N-channel 40 V 1.55 mΩ logic level MOSFET in LFPAK using NextPower technology

22 August 2012

Product data sheet

1. Product profile

1.1 General description

Logic level enhancement mode N-channel MOSFET in LFPAK package. This product is designed and qualified for use in a wide range of industrial, communications and domestic equipment.

1.2 Features and benefits

- High reliability Power SO8 package, qualified to 150°C
- Optimised for 4.5V Gate drive utilising NextPower Superjunction technology
- Ultra low QG, QGD, & QOSS for high system efficiencies at low and high loads
- Ultra low Rdson and low parasitic inductance

1.3 Applications

- DC-to-DC converters
- Load switching
- Power OR-ing
- Server power supplies
- Sync rectifier

1.4 Quick reference data

| Symbol | Parameter | Conditions | | Min | Тур | Max | Unit |
|-------------------|----------------------------------|--|-----|-----|------|------|------|
| V _{DS} | drain-source voltage | 25 °C ≤ T _j ≤ 150 °C | | - | - | 40 | V |
| ID | drain current | T _{mb} = 25 °C; V _{GS} = 10 V; <u>Fig. 1</u> | [1] | - | - | 100 | Α |
| P _{tot} | total power dissipation | T _{mb} = 25 °C; <u>Fig. 2</u> | | - | - | 288 | W |
| Tj | junction temperature | | | -55 | - | 150 | °C |
| Static chara | acteristics | 1 | | | | | |
| R _{DSon} | drain-source on-state resistance | V _{GS} = 4.5 V; I _D = 25 A; T _j = 25 °C; Fig. 12 | | - | 1.45 | 1.8 | mΩ |
| | | V _{GS} = 10 V; I _D = 25 A; T _j = 25 °C; Fig. 12 | | - | 1.25 | 1.55 | mΩ |
| Dynamic cl | naracteristics | · | | | | _ | |
| Q _{GD} | gate-drain charge | V_{GS} = 4.5 V; I _D = 25 A; V _{DS} = 20 V; Fig. 14 | | - | 15.3 | - | nC |



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| Symbol | Parameter | Conditions | Min | Тур | Max | Unit |
|---------------------|-------------------|---|-----|-----|-----|------|
| Q _{G(tot)} | total gate charge | V_{GS} = 4.5 V; I _D = 25 A; V _{DS} = 20 V; Fig. 14 | - | 59 | - | nC |

[1] Continuous current is limited by package.

2. Pinning information

| Table 2. | Pinning | information | | |
|----------|---------|-----------------------------------|--------------------------------|----------------|
| Pin | Symbol | Description | Simplified outline | Graphic symbol |
| 1 | S | source | | D |
| 2 | S | source | | |
| 3 | S | source | | G-UF 44 |
| 4 | G | gate | | mbb076 S |
| mb | D | mounting base; connected to drain | | |
| | | | LFPAK; Power- SO8 (SOT1023) | |

3. Ordering information

| Table 3. | Ordering information |
|----------|----------------------|
| | |

| Type number | Package | | |
|---------------|---------------------|---|---------|
| | Name | Description | Version |
| PSMN1R6-40YLC | LFPAK; Power-SO8 | Plastic single-ended surface-mounted package (LFPAK); 4 leads | SOT1023 |

4. Limiting values

Table 4. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134).

| Symbol | Parameter | Conditions | | Min | Max | Unit |
|------------------|-------------------------|--|-----|-----|------|------|
| V _{DS} | drain-source voltage | 25 °C ≤ T _j ≤ 150 °C | | - | 40 | V |
| V _{DGR} | drain-gate voltage | 25 °C \leq T _j \leq 150 °C; R _{GS} = 20 kΩ | | - | 40 | V |
| V _{GS} | gate-source voltage | | | -20 | 20 | V |
| I _D | drain current | V _{GS} = 10 V; T _{mb} = 25 °C; <u>Fig. 1</u> | [1] | - | 100 | А |
| | | V _{GS} = 10 V; T _{mb} = 100 °C; <u>Fig. 1</u> | [1] | - | 100 | А |
| I _{DM} | peak drain current | pulsed; $t_p \le 10 \ \mu s$; $T_{mb} = 25 \ ^{\circ}C$; Fig. 4 | | - | 1304 | А |
| P _{tot} | total power dissipation | T _{mb} = 25 °C; <u>Fig. 2</u> | | - | 288 | W |
| T _{stg} | storage temperature | | | -55 | 150 | °C |

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| Symbol | Parameter | Conditions | | Min | Мах | Unit |
|----------------------|---|---|-----|-----|------|------|
| Tj | junction temperature | | | -55 | 150 | °C |
| T _{sld(M)} | peak soldering temperature | | | - | 260 | °C |
| V _{ESD} | electrostatic discharge voltage | MM (JEDEC JESD22-A115) | | 1 | - | kV |
| Source-drain | diode | | | | | |
| I _S | source current | T _{mb} = 25 °C | [1] | - | 100 | А |
| I _{SM} | peak source current | pulsed; $t_p \le 10 \ \mu s$; $T_{mb} = 25 \ ^{\circ}C$ | | - | 1304 | А |
| Avalanche ru | uggedness | | | | | |
| E _{DS(AL)S} | non-repetitive drain-source avalanche energy | V_{GS} = 10 V; T _{j(init)} = 25 °C; I _D = 100 A; V _{sup} ≤ 40 V; R _{GS} = 50 Ω; unclamped; Fig. 3 | | - | 391 | mJ |

[1] Continuous current is limited by package.

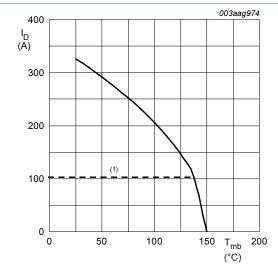


Fig. 1. Continuous drain current as a function of mounting base temperature

 $\label{eq:VGS} V_{GS} \! \geq \! 10 \, V$ (1) Capped at 100 A due to package.

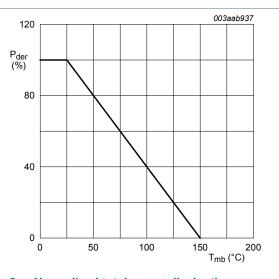
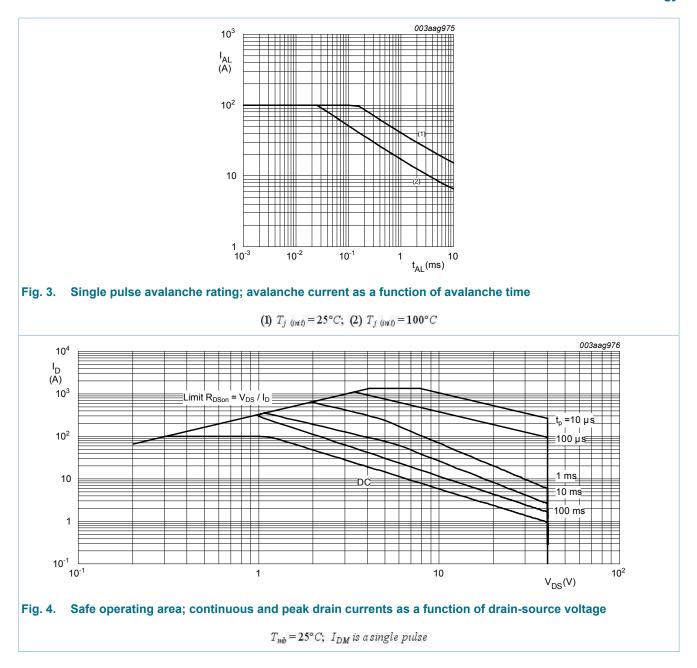


Fig. 2. Normalized total power dissipation as a function of solder point temperature

$$P_{der} = \frac{P_{tot}}{P_{tot(25^{\circ}C)}} \times 100 \%$$

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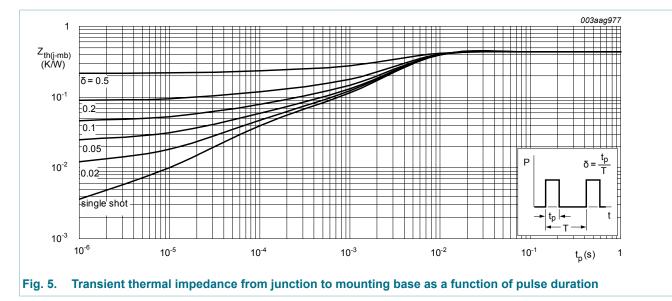
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5. Thermal characteristics

| Table 5. The | rmal characteristics | | | | | |
|-----------------------|---|---------------|-----|------|------|------|
| Symbol | Parameter | Conditions | Min | Тур | Max | Unit |
| R _{th(j-mb)} | thermal resistance from junction to mounting base | <u>Fig. 5</u> | - | 0.35 | 0.43 | K/W |

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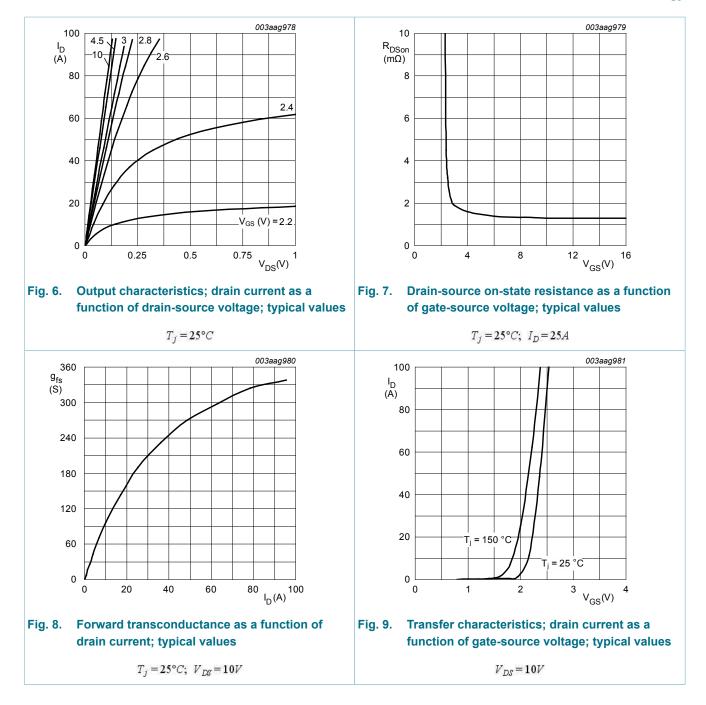
6. Characteristics

| Symbol | Parameter | Conditions | Min | Тур | Max | Unit |
|----------------------|----------------------------------|--|------|------|------|------|
| Static chara | acteristics | · · · | | | | |
| V _{(BR)DSS} | drain-source | I_D = 250 µA; V_{GS} = 0 V; T_j = 25 °C | 40 | - | - | V |
| | breakdown voltage | I_D = 250 µA; V_{GS} = 0 V; T_j = -55 °C | 36 | - | - | V |
| V _{GS(th)} | gate-source threshold voltage | I _D = 1 mA; V _{DS} = V _{GS} ; T _j = 25 °C; Fig. 10; Fig. 11 | 1.05 | 1.46 | 1.95 | V |
| | | I_D = 10 mA; V_{DS} = V_{GS} ; T_j = 150 °C | 0.5 | - | - | V |
| | | $I_D = 1 \text{ mA}; V_{DS} = V_{GS}; T_j = -55 \text{ °C}$ | - | - | 2.25 | V |
| I _{DSS} | drain leakage current | V_{DS} = 40 V; V_{GS} = 0 V; T_j = 25 °C | - | - | 1 | μA |
| | | V _{DS} = 40 V; V _{GS} = 0 V; T _j = 150 °C | - | - | 100 | μA |
| I _{GSS} | gate leakage current | V _{GS} = 16 V; V _{DS} = 0 V; T _j = 25 °C | - | - | 100 | nA |
| | | V_{GS} = -16 V; V_{DS} = 0 V; T_j = 25 °C | - | - | 100 | nA |
| R _{DSon} | drain-source on-state resistance | V _{GS} = 4.5 V; I _D = 25 A; T _j = 25 °C; Fig. 12 | - | 1.45 | 1.8 | mΩ |
| | | V _{GS} = 4.5 V; I _D = 25 A; T _j = 150 °C; Fig. 12; Fig. 13 | - | - | 3.2 | mΩ |
| | | V _{GS} = 10 V; I _D = 25 A; T _j = 25 °C; Fig. 12 | - | 1.25 | 1.55 | mΩ |
| | | V _{GS} = 10 V; I _D = 25 A; T _j = 150 °C; Fig. 12; Fig. 13 | - | - | 2.7 | mΩ |
| R _G | gate resistance | f = 1 MHz | - | 1.17 | 2.34 | Ω |

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| Symbol | Parameter | Conditions | Min | Тур | Max | Unit |
|------------------------|---------------------------------------|---|-----|------|-----|------|
| Dynamic cł | naracteristics | · · · · · · · · · · · · · · · · · · · | | | | |
| Q _{G(tot)} | total gate charge | I _D = 25 A; V _{DS} = 20 V; V _{GS} = 10 V; Fig. 14; Fig. 15 | - | 126 | - | nC |
| | | I_D = 25 A; V_{DS} = 20 V; V_{GS} = 4.5 V; Fig. 14 | - | 59 | - | nC |
| | | $I_D = 0 A; V_{DS} = 0 V; V_{GS} = 10 V$ | - | 115 | - | nC |
| Q _{GS} | gate-source charge | I_D = 25 A; V_{DS} = 20 V; V_{GS} = 4.5 V; | - | 17.7 | - | nC |
| Q _{GS(th)} | pre-threshold gate- source charge | Fig. 14 | - | 12.5 | - | nC |
| Q _{GS(th-pl)} | post-threshold gate- source charge | | - | 5.2 | - | nC |
| Q _{GD} | gate-drain charge | | - | 15.3 | - | nC |
| V _{GS(pl)} | gate-source plateau voltage | I _D = 25 A; V _{DS} = 20 V; <u>Fig. 14</u> | - | 2.4 | - | V |
| C _{iss} | input capacitance | V_{DS} = 20 V; V_{GS} = 0 V; f = 1 MHz; | - | 7790 | - | pF |
| C _{oss} | output capacitance | $V_{DS} = 25 \text{ °C}; V_{GS} = 0 \text{ V}, 1 = 110112,$ $T_j = 25 \text{ °C}; Fig. 16$ | - | 1063 | - | pF |
| C _{rss} | reverse transfer capacitance | | - | 409 | - | pF |
| t _{d(on)} | turn-on delay time | V_{DS} = 20 V; R _L = 0.8 Ω; V _{GS} = 4.5 V; | - | 41 | - | ns |
| t _r | rise time | $R_{G(ext)} = 4.7 \Omega$ | - | 48 | - | ns |
| t _{d(off)} | turn-off delay time | | - | 86 | - | ns |
| t _f | fall time | - | - | 42 | - | ns |
| Q _{oss} | output charge | V_{GS} = 0 V; V_{DS} = 20 V; f = 1 MHz; T _j = 25 °C | - | 38.7 | - | nC |
| Source-dra | in diode | | | | | |
| V _{SD} | source-drain voltage | I_{S} = 25 A; V_{GS} = 0 V; T_{j} = 25 °C; <u>Fig. 17</u> | - | 0.77 | 1.1 | V |
| t _{rr} | reverse recovery time | $I_{S} = 25 \text{ A}; \text{ d}I_{S}/\text{d}t = -100 \text{ A}/\mu\text{s}; \text{ V}_{GS} = 0 \text{ V}; \\ \text{V}_{DS} = 20 \text{ V}; \text{ Fig. 18}$ | - | 44 | - | ns |
| Q _r | recovered charge | I _S = 25 A; dI _S /dt = -100 A/µs; V _{GS} = 0 V; V _{DS} = 20 V | - | 62 | - | nC |
| t _a | reverse recovery rise time | V_{GS} = 0 V; I _S = 25 A; dI _S /dt = -100 A/µs; V _{DS} = 20 V; Fig. 18 | - | 26 | - | ns |
| t _b | reverse recovery fall time | | - | 18 | - | ns |

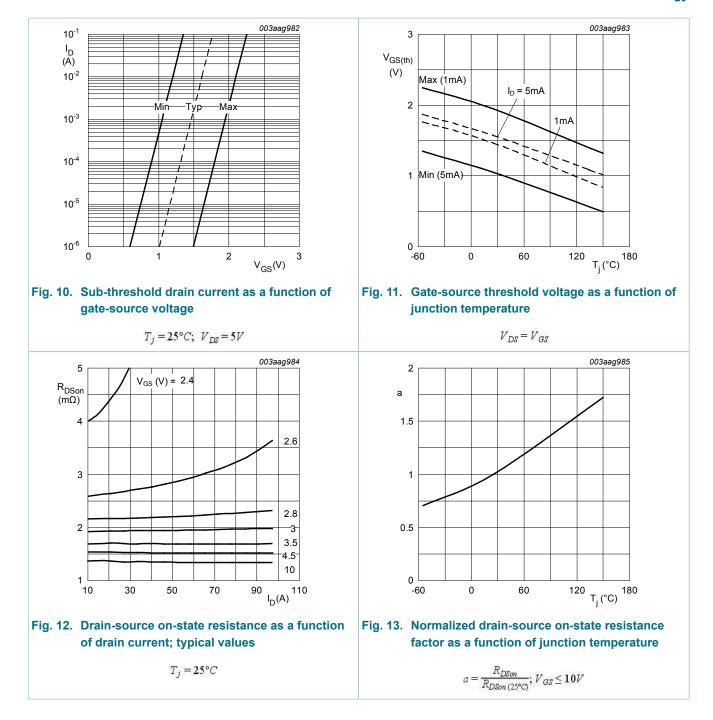
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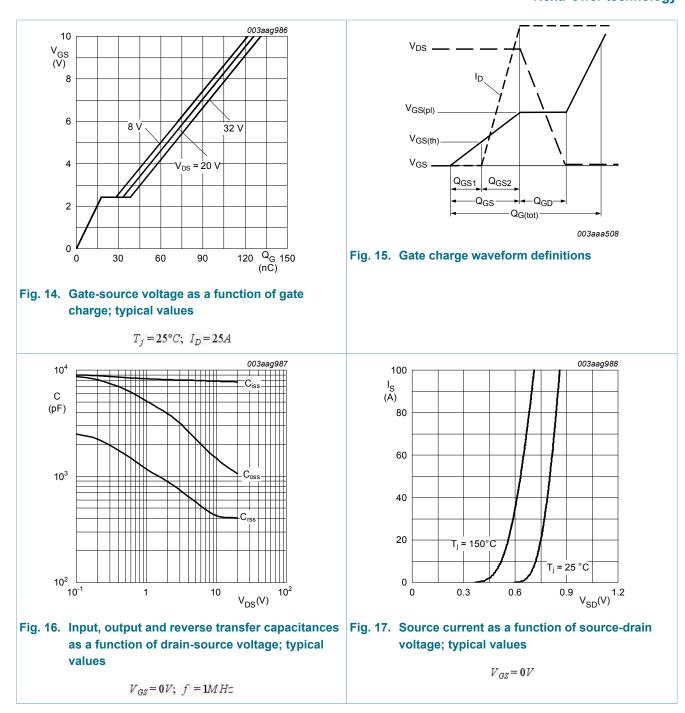
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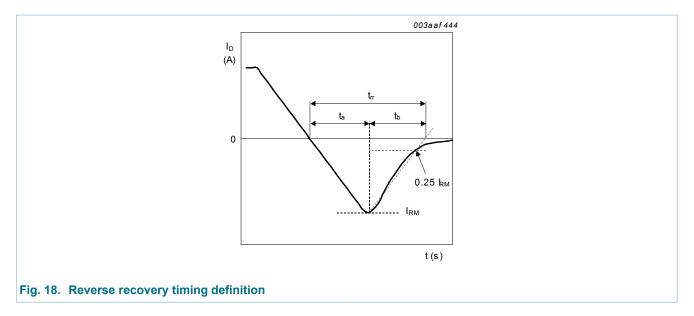
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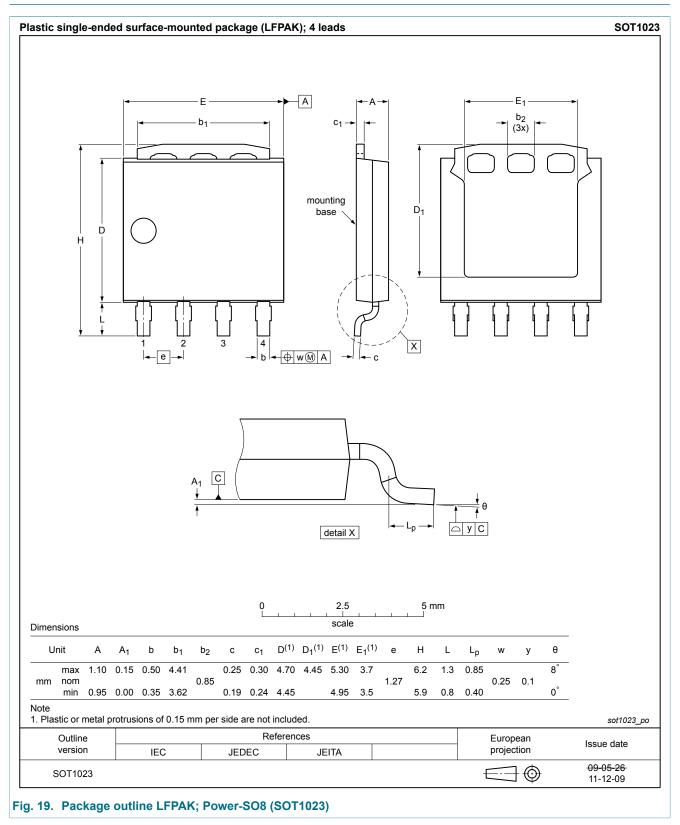
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7. Package outline



PSMN1R6-40YLC

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|--------------------------------------|-------------------------------|---|
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